TECHNOLOGY

Method for Re-metallizing Aluminum and Aluminum Alloy Bond Pads

OVERVIEW

The present invention is a method for re-metallizing the bond pads of electronic chips which are metallized with aluminum or aluminum alloys such as Al/Si/Cu. Unlike most existing techniques, the invention does not sacrifice wire bondability. The invention is a sequence of electrochemical treatments which selectively covers the chip bond pads with gold, which is both wire bondable and flip chip bondable.

The invention is available for immediate application. It can also be used for the re-metallization of singulated dies and full wafers. Further, it can be applied to various aluminum alloys and can use platinum or palladium rather than gold.

For additional information please contact the Office of Technology Commercialization, University of Maryland, College Park, MD 20742. Phone (301) 405-3947. E-mail: otc@umd.edu.

CONTACT INFO

UM Ventures
0134 Lee Building
7809 Regents Drive
College Park, MD 20742
Email: umdtechtransfer@umd.edu
Phone: (301) 405-3947 | Fax: (301) 314-9502

Additional Information

INSTITUTION

University of Maryland, College Park

PATENT STATUS

Patent(s) pending

LICENSE STATUS

Available for exclusive license

CATEGORIES

- Microelectronics

EXTERNAL RESOURCES

PS-97-084